ANALOG DEVICES

Reliability Qualification Plan for
Stacked-die LFCSP Package at STATS ChipPAC China (SCC)

QUALIFICATION PLAN			
Test	Conditions	Sample Size	Expected Completion Date
Highly Accelerated Stress Test (HAST)*	JEDEC *JESD22-A110*	**3 x 77**	April 2014
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	**3 x 77**	April 2014
Autoclave (AC)*	JEDEC *JESD22-A102*	**3 x 77**	April 2014
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	**3 x 11**	April 2014
High Temperature Storage Life (HTSL)	JEDEC *JESD22-A103*	**1 x 77**	April 2014
Field Induced Charged Device Model (FICDM)	JEDEC *JESD22-C101*	**3/Voltage**	April 2014

*Preconditioned per JEDEC/IPC J-STD-020